

拆封後產品使用期限 (Product use time limit after unpacking)

產品於松翰要求之儲存環境條件下，拆封後之產品使用期限如下：

Product keep in SONiX required storage condition, the use time limit of unpacked product as below

◎ 晶圓/晶粒產品：5天

For Wafer/Chip product : 5 days

◎ 真空包裝封裝產品：5天

For Vacuum packing package : 5 days

拆封後產品超過使用期限處置

(Disposition when Unpack Product Exceed Time Limit)

當拆封產品超過松翰科技訂定使用期限，建議處置如下：

When unpacked product exceeds the product use time limit specified by SONiX, it is recommended to dispose of it as follows.

◎晶圓/晶粒產品(For Wafer/Chip product)

無法保證產品品質

Product quality cannot be guaranteed.

◎真空包裝封裝產品(For Vacuum packing package)

重新以 125 ± 5 °C /12小時烘烤後，並儘速使用完畢

After re-baking at 125 ± 5 °C /12 hours, use it up as soon as possible.